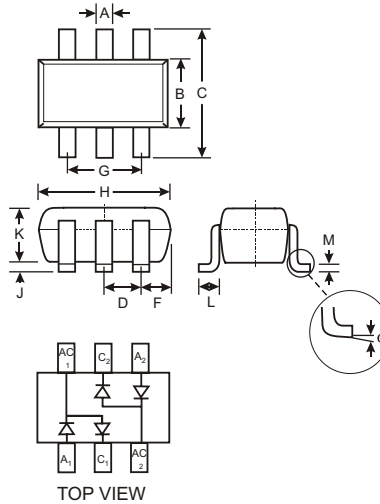


Features

- Fast Switching Speed
- Ultra-Small Surface Mount Package
- For General Purpose Switching Applications
- High Conductance
- Two “BAV99” Circuits In One Package
- Available in Lead Free Version

Mechanical Data

- Case: SOT-363, Molded Plastic
- Case Material - UL Flammability Rating Classification 94V-0
- Moisture sensitivity: Level 1 per J-STD-020A
- Terminals: Solderable per MIL-STD-202, Method 208
- Also Available in Lead Free Plating (Matte Tin Finish). Please See Ordering Information, Note 5, on Page 3
- Polarity: See Diagram
- Marking: KJG (See Page 3)
- Weight: 0.006 grams (approx.)



SOT-363		
Dim	Min	Max
A	0.10	0.30
B	1.15	1.35
C	2.00	2.20
D	0.65 Nominal	
E	0.30	0.40
G	1.80	2.20
H	1.80	2.20
J	—	0.10
K	0.90	1.00
L	0.25	0.40
M	0.10	0.25
α	0°	8°
All Dimensions in mm		

Maximum Ratings @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V _{RM}	100	V
Peak Repetitive Reverse Voltage	V _{RRM}	75	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	53	V
Forward Continuous Current (Note 1)	I _{FM}	215	mA
Non-Repetitive Peak Forward Surge Current @ t = 1.0μs @ t = 1.0ms @ t = 1.0s	I _{FSM}	2.0 1.0 0.5	A
Power Dissipation (Note 1)	P _d	200	mW
Thermal Resistance Junction to Ambient Air (Note 1)	R _{θJA}	625	°C/W
Power Dissipation (Note 2)	P _d	300	mW
Thermal Resistance Junction to Ambient Air (Note 2)	R _{θJA}	417	°C/W
Operating and Storage Temperature Range	T _j , T _{STG}	-65 to +150	°C

Electrical Characteristics @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 3)	V _{(BR)R}	75	—	V	I _R = 2.5μA
Forward Voltage (Note 3)	V _F	—	0.715 0.855 1.0 1.25	V	I _F = 1.0mA I _F = 10mA I _F = 50mA I _F = 150mA
Reverse Current (Note 3)	I _R	—	2.5 50 30 25	μA μA μA nA	V _R = 75V V _R = 75V, T _j = 150°C V _R = 25V, T _j = 150°C V _R = 20V
Total Capacitance	C _T	—	2.0	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	4.0	ns	I _F = I _R = 10mA, I _{rr} = 0.1 x I _R , R _L = 100Ω

- Notes:
1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 2. Device mounted on Alumina PCB, 0.4 inch x 0.3 inch x 0.024 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 3. Short duration test pulse used to minimize self-heating effect.

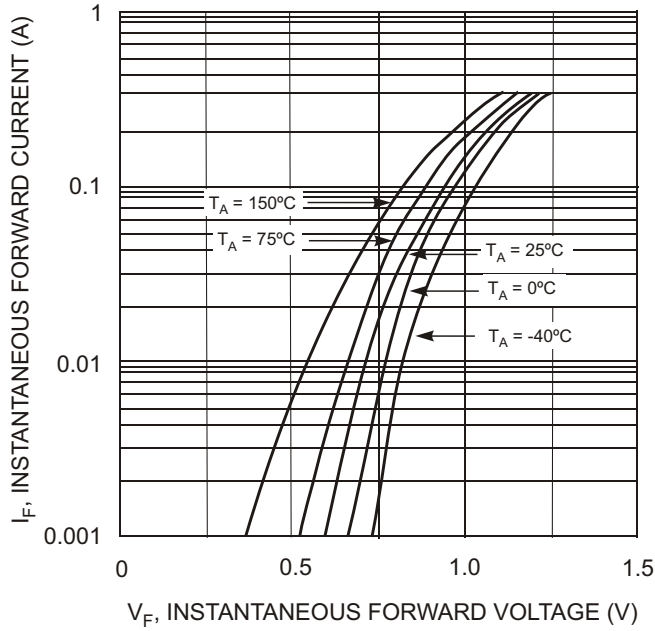


Fig. 1 Forward Characteristics

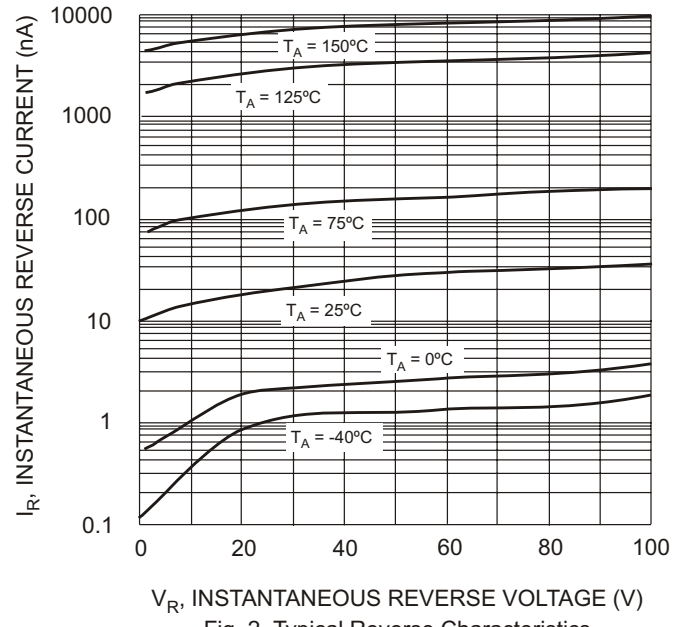


Fig. 2 Typical Reverse Characteristics

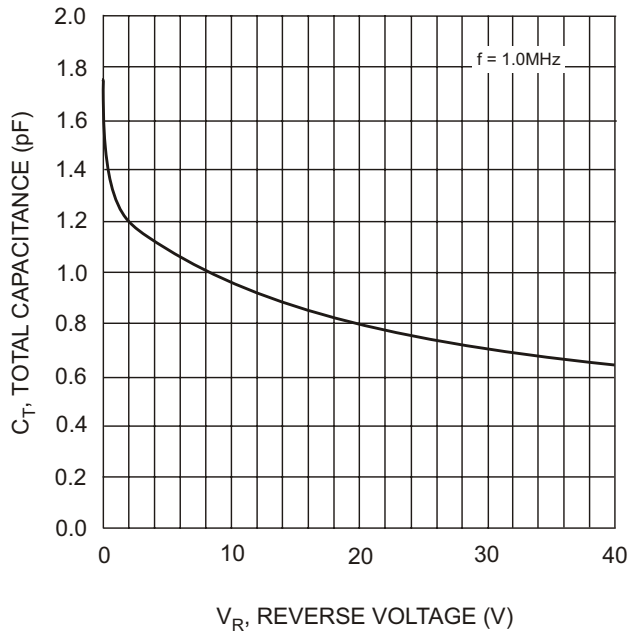


Fig. 3 Typical Capacitance vs. Reverse Voltage

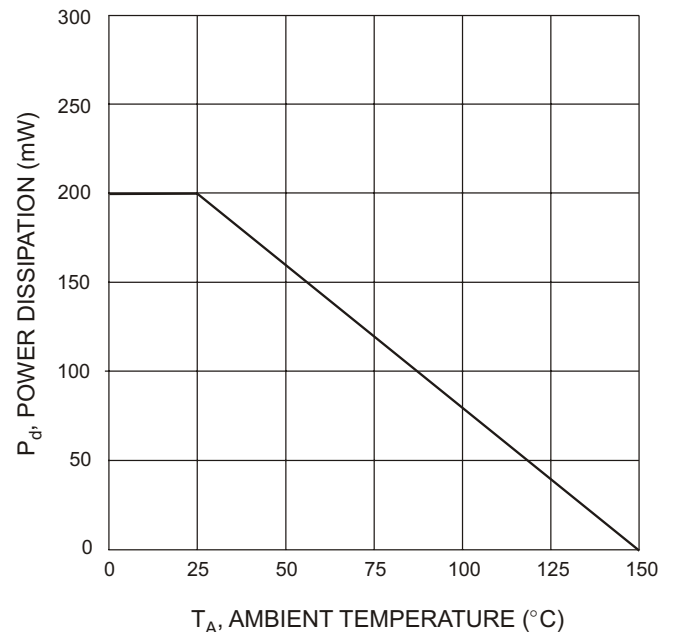


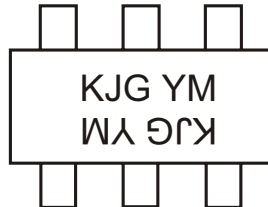
Fig. 4 Power Derating Curve

Ordering Information (Note 4 & 5)

Device	Packaging	Shipping
BAV99DW-7	SOT-363	3000/Tape & Reel

- Notes: 4. For Packaging Details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.
 5. For lead free terminal plating part number, please add "-F" suffix to part number above. Example: BAV99DW-7-F.

Marking Information



KJG = Product Type Marking Code
 YM = Date Code Marking
 Y = Year ex: N = 2002
 M = Month ex: 9 = September

Date Code Key

Year	2001	2002	2003	2004	2005	2006	2007	2008	2009
Code	M	N	P	R	S	T	U	V	W

Month	Jan	Feb	March	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D